

# PATENT ABSTRACTS OF JAPAN

(11) Publication number : 64-054749  
 (43) Date of publication of application : 02.03.1989

(51) Int.CI.

H01L 23/28  
 H01L 21/60  
 H01L 23/50

(21) Application number : 62-211993  
 (22) Date of filing : 26.08.1987

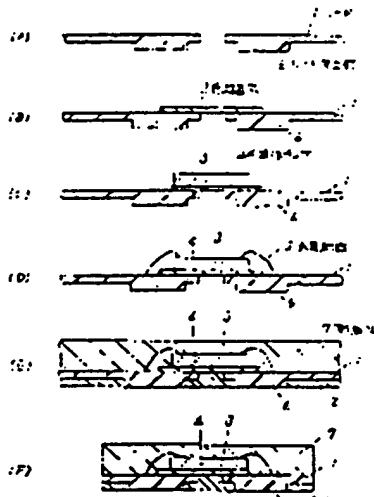
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## (54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

### (57) Abstract:

**PURPOSE:** To obtain a highly accurate and highly reliable semiconductor device by placing a semiconductor chip through an insulating substrate on one group of highly accurate metal leads, connecting the leads to fine metal wirings, and transfer molding them.

**CONSTITUTION:** A thin resin plate 3 is attached to leads 1 having protrusions 6, and electrodes on a semiconductor chip 4 are connected to the leads 1 by fine metal wirings 5. Then, the leads except the protrusions 6 are sealed with resins 2, 7, shape and size are determined and cut. According to this structure, a small-sized and thin semiconductor device having high dimensional accuracy and reliability is obtained without complicated structure like a both-side substrate only by employing metal leads of special shape at part, and is preferably adapted for an IC.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

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[Number of appeal against examiner's decision of rejection]

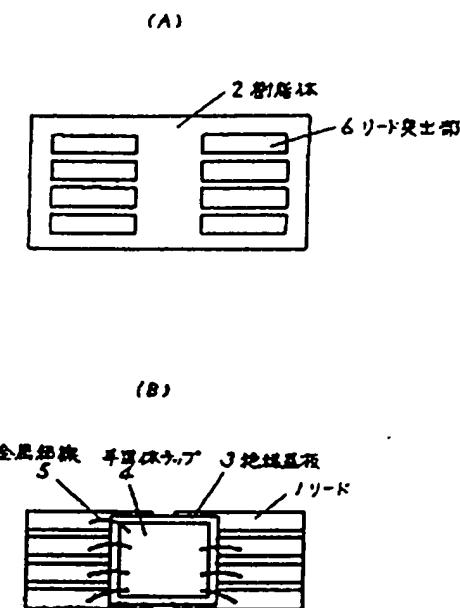
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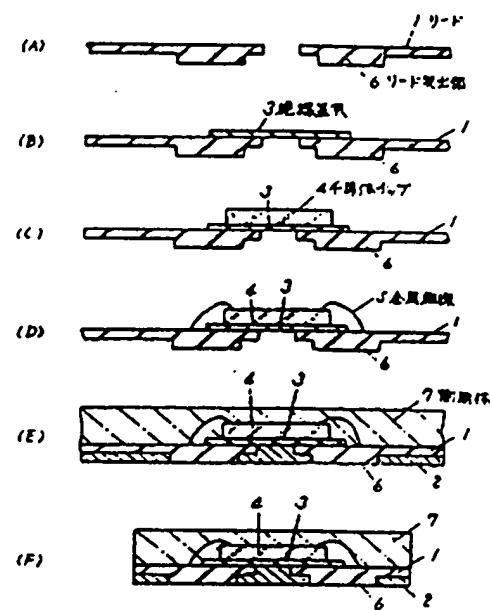
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第2図



第3図



第4図

